REMARKS

The courtesy of the Examiner in granting the undersigned attorney a personal interview on May 8, 2006 is gratefully acknowledged. During that interview, the language of Claim 1 was discussed in light of the art of record. As noted on the Examiner Interview Summary Record, it was agreed that the claims would be amended to clarify that the invention is directed to a laminate structure that includes both a surface resin layer and a resin conducting layer.

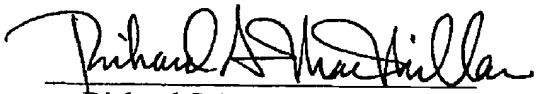
During the interview, it was also agreed that revised drawings in accordance with the parent P.C.T. application would be filed. Such replacement drawings are being filed concurrently herewith.

As discussed during the interview, independent Claim 1 has been amended to define the invention as a laminate surface material that is adapted to provide an in-mold surface coating for use with a molding material. The laminate surface material includes a layer of a surface resin material and a resin conducting layer. The resin conducting layer includes a venting structure that allows for venting gases during processing of the surface material such that no voids are formed during the processing of the surface material. The resin conducting layer further provides a resin retention structure for retaining the surface resin material in contact with the mold surface during processing of the surface material, wherein the resin conducting layer includes a woven or non-woven thermo-plastic fabric material. Independent Claims 3, 16, and 21 have been amended in a similar manner. Independent Claim 22 has been amended to recite that the laminate preform surface material, which is adapted to provide an in-mold surface coating, includes a layer of a surface resin material and a resin retention layer that includes a resin retention structure for retaining the resin material into contact with the mold surface during processing of the surface material. As a result, no voids are formed during the processing of the surface material. Also, the resin structure is adapted to reduce the tendency for the formation of surface irregularities during processing.

The Ness et al. reference does not show or suggest the invention as now claimed. Specifically, the Ness et al. reference does not show or suggest a laminate

surface material that includes (1) a layer of a surface resin material and (2) a resin conducting layer, wherein the resin conducting layer both (a) comprises a venting structure that allows for venting gases during processing of the surface material such that no voids are formed during the processing of said surface material and (b) provides a resin retention structure for retaining the surface resin material in contact with the mold surface during processing of the surface material, as recited in independent Claims 1, 3, 16, and 21. Similarly, the Ness et al. reference does not show or suggest a resin retention layer comprising a resin retention structure for both retaining the resin material into contact with the mold surface during processing of the surface material such that no voids are formed during the processing of said surface material and reducing the tendency for the formation of surface irregularities during processing, as recited in independent Claim 22. Thus, it is believed that the claims are patentable over the Ness et al. reference.

Respectfully submitted,



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